



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-03-23
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7NC5*Z73Q83Y	A	ZA41	2016-03-23
Amount	UoM	Unit type	ST ECOPACK Grade	
35.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFJ	4.14,2.76,1.94	1	J bend	
Comment	SMA Flat 2 Leads No exposed pad; MD valid for CP : STPS2L40AF.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7NCS*Z73Q83Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	1.653	mg	supplier	Die	Silicon (Si)	7440-21-3		1.585	mg	958863	45286
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	6655	314
Silicon die				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1210	57
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	1815	86
Silicon die				supplier	metallization	Nickel (Ni)	7440-02-0		0.008	mg	4840	229
Silicon die				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	4840	229
Silicon die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.011	mg	6655	314
Silicon die				supplier	back metallization	Titanium (Ti)	7440-32-6		0.001	mg	605	29
Silicon die				supplier	back metallization	Gold (Au)	7440-57-5		0.002	mg	1210	57
Silicon die				supplier	back metallization	Nickel (Ni)	7440-02-0		0.011	mg	6655	314
Silicon die				supplier	passivation	Esterified polyamid	63428-83-1		0.01	mg	6050	286
Silicon die				supplier	passivation	Tetraethylene glycol dimethacrylate	109-17-1		0.001	mg	605	29
Leadframe	Copper & its alloys	14.828	mg	supplier	Frame Alloy	Cu	7440-50-8		14.806	mg	998516	423029
Leadframe				supplier	Frame Alloy	Fe	7439-89-6		0.015	mg	1012	429
Leadframe				supplier	Frame Alloy	P	7723-14-0		0.007	mg	472	200
Die attach	Other Organic Materials	2.552	mg	supplier	soft solder	Pb	7439-92-1	7a-Lead in high me	2.361	mg	925157	67457
Die attach				supplier	soft solder	Sn	7440-31-5		0.128	mg	50157	3657
Die attach				supplier	soft solder	Ag	7440-22-4		0.063	mg	24687	1800
Encapsulation	Other inorganic materials	15.345	mg	supplier	Moulding Compound	Silica , amorphous,fused	60676-86-0		12.276	mg	800000	350743
Encapsulation				supplier	Moulding Compound	Epoxy resin propietare,resin unknow	29690-82-2		2.071	mg	134963	59171
Encapsulation				supplier	Moulding Compound	Benzophenone teracarboxylic anhydride	2421-28-5		0.154	mg	10036	4400
Encapsulation				supplier	Moulding Compound	Silica, quartz	14808-60-7		0.69	mg	44966	19714
Encapsulation				supplier	Moulding Compound	Carbon black	1333-86-4		0.154	mg	10036	4400
Finishing	Solder	0.622	mg	supplier	Connection Coating	Sn	7440-31-5		0.622	mg	1000000	17771